CMOS Dual Precision Monostable Multivibrator

High-Voltage Types (20-Volt Rating)

Features:

- Retriggerable/resettable capability
- Trigger and reset propagation delays independent of R_x, C_X
- Triggering from leading or trailing edge
- Q and Q buffered outputs available
- Separate resets
- Replaces CD4538B Type

■ CD14538B dual precision monostable multivibrator provides stable retriggerable/resettable one-shot operation for any fixed-voltage timing application.

An external resistor (R_X) and an external capacitor (C_X) control the timing and accuracy for the circuit. Adjustment of R_X and C_X provides a wide range of output pulse widths from the Q and \overline{Q} terminals. The time delay from trigger input to output transition (trigger propagation delay) and the time delay from reset input to output transition (reset propagation delay) are independent of R_X and C_X . Precision control of output pulse widths is achieved through linear CMOS techniques.

Leading-edge-triggering (+TR) and trailing-edge-triggering (-TR) inputs are provided for triggering from either edge of an input pulse. An unused +TR input should be tied to V_{SS} . An unused -TR input should be tied to V_{DD} . A RESET (on low level) is provided for immediate termination of the output pulse or to prevent output pulses when power is turned on. An unused RESET input should be tied to V_{DD} . However, if an entire section of the CD14538B is not used, its inputs must be tied to either V_{DD} or V_{SS} . See Table I.

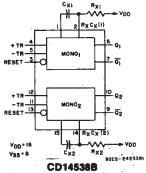
In normal operation the circuit retriggers (extends the output pulse one period) on the application of each new trigger pulse. For operation in the non-retriggerable mode, \overline{Q} is connected to -TR when leading-edge triggering (+TR) is used or \overline{Q} is connected to +TR when trailing-edge triggering (-TR) is used. The time period (T) for this multivibrator can be calculated by: $T = R_x C_x$.

The minimum value of external resistance, R_x , is 4 K Ω . The minimum and maximum values of external capacitance, C_x , are 0 pF and 100 μ F, respectively.

The CD14538B is interchangeable with type MC14538 and is similar to and pin-compatible with the CD4098B* and CD4538B. It can replace the CD4538B which type is not recommended for new designs.

The CD14538B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

*T = 0.5 R_xC_x for $C_x \ge 1000 pF$ #T = R_xC_x ; $C_xmin = 5000 pF$



- **FUNCTIONAL DIAGRAM**
 - Wide range of output-pulse widths
 - Schmitt-trigger input allows unlimited rise and fall times on +TR and -TR inputs
 - 100% tested for maximum quiescent current at 20 V
 - Maximum input current of 1 µA at 18 V over full package-temperature range; 100 nA at 18 V and 25° C
 - Noise margin (full package-temperature range):

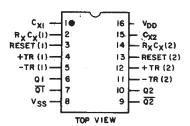
1 V at
$$V_{DD} = 5 V$$

2 V at $V_{DD} = 10 V$

- $2.5 \text{ V at } V_{DD} = 15 \text{ V}$
- 5-V, 10-V, and 15-V parametric ratings
- Standardized, symmetrical output characteristics
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."

Applications:

- Pulse delay and timing
- Pulse shaping



TERMINALS 1,8,15 ARE ELECTRICALLY CONNECTED INTERNALLY 92CS-24848RI

Terminal Assignment

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V _{DD})	
Voltages referenced to VSS Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	+0.5V to Vnn +0.5V
DC INPUT CURRENT, ANY ONE INPUT	+10mA
POWER DISSIPATION PER PACKAGE (PD):	
POWER DISSIPATION PER PACKAGE (PD): For TA = -55°C to +100°C For Ta = +100°C to +125°C Perot	500mW
For TA = +100°C to +125°C	e Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) OPERATING-TEMPERATURE RANGE (T _A)	
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types). OPERATING-TEMPERATURE RANGE (T _A) STORAGE TEMPERATURE RANGE (T _{Stg}) LEAD TEMPERATURE (DURING SOLDERING): At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operating is always within the following ranges:

CHARACTERISTIC	V _{DO}	LIMITS		UNITS
CHARACTERISTIC	(V)	Min.	Max.	UNITS
Supply-Voltage Range (For T _A =Full Package-Temperature Range)		3	18	y
Input Pulse Width twh, twL	 5	140		,
+TR, -TR, or RESET	 10	80	_	ns
	15	60		

TABLE I CD4538B FUNCTIONAL TERMINAL CONNECTIONS

FUNCTIION	V _{DD} TO TERM. NO.		V _{SS} TO TERM. NO.		INPUT PULSE TO TERM. NO.		OTHER CONNECTIONS	
	MONO1	MONO ₂	MONO ₁	MONO ₂	MONO:	MONO ₂	MONO1	MONO ₂
Leading-Edge Trigger/ Retriggerable	3, 5	11, 13			4	12		
Leading-Edge Trigger/ Non-Retriggerable	3	13		1	4	12	5-7	11-9
Trailing-Edge Trigger/ Retriggerable	3	. 13	4	12	5	11		
Trailing-Edge Trigger/ Non-Retriggerable	3	13	ž		5	11	4-6	12-10

NOTES:

- 1. A RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS AN OUTPUT PULSE WIDTH WHICH IS EXTENDED ONE FULL TIME PERIOD (T) AFTER APPLICATION OF THE LAST TRIGGER PULSE.
- 2. A NON—RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS A TIME PERIOD (T) REFERENCED FROM THE APPLICATION OF THE FIRST TRIGGER PULSE.

INPUT PULSE TRAIN

RETRIGGERABLE MODE PULSE WIDTH (+TR MODE) NON-RETRIGGERABLE MODE PULSE WIDTH

(+TR MODE)

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CO	NDITIO	NS	LIN	LIMITS AT INDICATED TEMPERATURES (°C)						
	V ₀ (V)	V _{IN} (V)	(V)	-55	-40	+85	+125	Min.	+25 Typ.	Max.	
		0.5	5	5	5	150	150	_	0.04	5	
Quiescent Device	_	0,10	10	10	10	300	300	_	0.04	10	1
Current, IDD Max.	_	0,15	15	20	20	600	600	_	0.04	20	μΑ
	_	0,20	20	100	100	3000	3000	_	0.08	100	1
Output Low (Sink)	0.4	0,5	5 .	0.64	0.61	0.42	0.36	0.51	1		
Output Low (Sink) Current, IoL Min.	0.5	0,10	10	1.6	1.5	-1.1	0.9	1.3	2.6		1
Current, IOL Mitt.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8		1
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	· -1	_	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		1
	9.5	0,10	_10	-1.6	-1.5	≐1.1	-0.9	-1.3	-2.6		
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	_	
Output Voltage:		0,5	5		0.	05		_	0	0.05	
Low-Level, Vol. Max.		0,10	10		0.	05		_	0	0.05	1
LOW-Level, VOL WAX.	_	0,15	15		0.	05		_	0	0.05	1
Output Voltage:		0,5	5	4.95 4.95 5 —						_	v
High-Level, Von Min.		0,10	10		9.95 9.9					_	1 ×
Tingit-Level, Von Willi.		0,15	15		14.95 14.95 1						1
Input Low Voltage,	0.5,4.5	-	5		1.5 — — 1					1.5	
V _{IL} Max.	1,9		10			3		_	_	3	1
AIF MAY.	1.5,13.5	_	. 15		4	4		<i>→</i> .		4] _v
Input High Voltage,	0.5,4.5		- 5	3.5 3.5 — —] v		
	1,9	_	10		7					_	
	1.5,13.5	_	15		1	1		11	_	— ,	
Input Current, I _{IN} Max.	-	0,18	18	±0.1	±0.1	±1	±1	_	±10 ⁻⁵	±0.1	μΑ

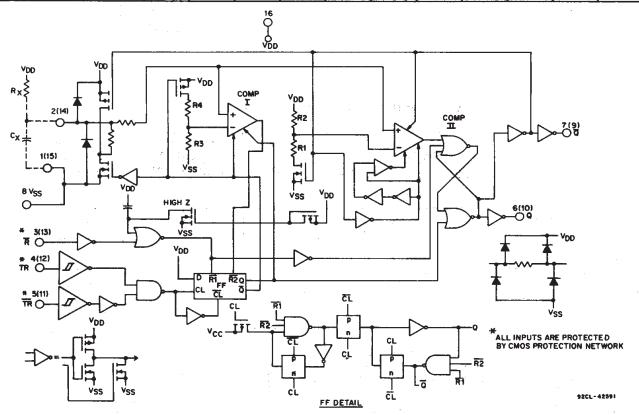


Fig. 1 - Logic diagram (½ of device shown).

DYNAMIC ELECTRICAL CHARACTERISTICS, At TA=25°C; Input tr,tr=20 ns, CL=50 pF

CHARACTERISTIC	TEST CONDITIONS						
CHARACTERISTIC	V _{DD} (V)	Min.	Тур.	Max.	UNITS		
Transition Time ttlh, tthL	5	_	100	200			
	10	_	50	100			
	15	_	40	80			
Propagation Delay Time: tell, tell	5	_	300	600	7		
+TR or -TR to Q or Q	10	_	150	300			
	15		100	220	ns		
Reset to Q or Q	5	_	250	500	1		
	10	_	125	250			
	15	_	95	190			
Minimum Input Pulse Width: twh, twL	5	_	80	140	1		
+TR, -TR or Reset	10	_	40	80			
	15	_	30	60			
Output Pulse Width - Q or Q: T	5	198	210	230	1		
$C_X = 0.002 \mu F$, $R_X = 100 K\Omega$	10	200	212	232	μs		
	15	202	214	234			
C _x =0.1 μF, R _x =100 KΩ	5	9.4	9.97	10.5	1		
	10	9.4	9.95	10.6	ms		
	15	9.5	10	10.6	i		
C _x =10 μF, R _x =100 KΩ	5	0.95	1	1.06			
	10	0.95	1	1.06	s		
	15	0.96	1.01	1.07			
Pulse Width Match between 100 (T ₁ -T ₂)	5	_	±1				
circuits in same package:	10	_	±1	_	%		
C _x =0.1 μF, R _x =100 KΩ	15	_	±1	-			
Minimum Retrigger Time t _{rr}	5	0	-	_			
	10	0	_	-	ns		
	15	0					
Input Capacitance C _{IN}	Any Input	_	5	7.5	pF		

^{*}Note: Minimum R_x value=4 $K\Omega$, minimum C_x value=5000 pF.

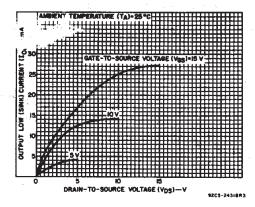


Fig. 2 - Typical output low (sink) current characteristics.

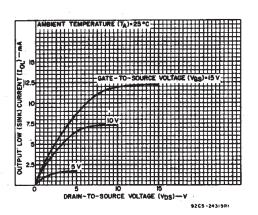


Fig. 3 - Minimum output low (sink) current characteristics.

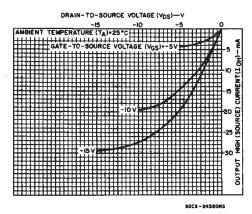


Fig. 4 - Typical output high (source) current characteristics.

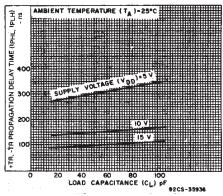


Fig. 6 - Typical propagation delay time as a function of load capacitance (+TR or -TR to Q or \overline{Q}).

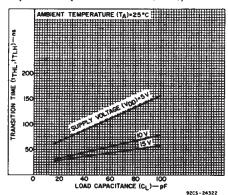


Fig. 8 - Typical transition time as a function of load capacitance.

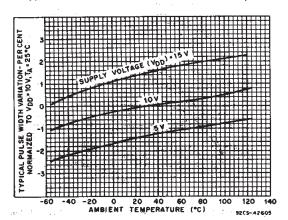


Fig. 10 - Typical pulse-width variation as a function of temperature (R_x =100 K Ω , C_x =0.1 μF).

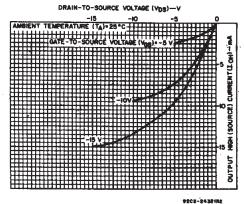


Fig. 5 - Minimum output high (source) current characteristics.

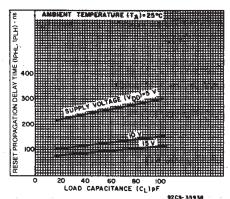


Fig. 7 - Typical propagation delay time as a function of load capacitance (RESET to Q or Q).

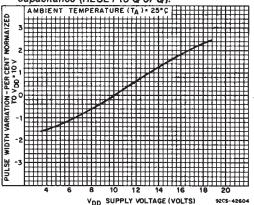


Fig. 9 - Typical pulse-width variation as a function of supply voltage.

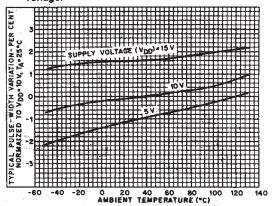


Fig. 11 - Typical pulse-width variation as a function of temperature (R_X =100 K Ω , C_X =2000 pF).

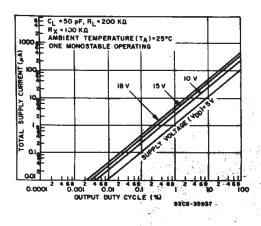


Fig. 12 - Typical total supply current as a function of output duty cycle.

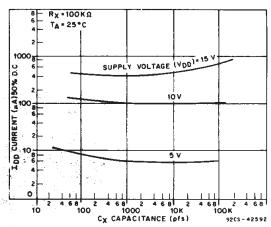
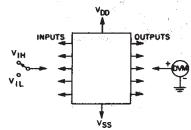


Fig. 13 - Typical total supply current as a function of load capacitance.



92CS-27441RI

NOTE:

- 1. Test any combination of inputs.
- 2. When measuring V_{IH} or V_{IL} for Schmitt trigger inputs (+TR, -TR), the input must first be brought to V_{DD} or V_{SS} , respectively, then reduced to the specified limit.

Fig. 14 - Input voltage test circuit.

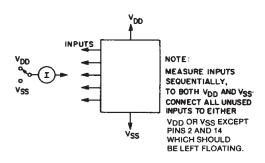


Fig. 15 - Input leakage-current test circuit.

VDD INPUTS VSS 92C5-274

Fig. 16 - Quiescent device current test circuit.

Power-Down Mode

During a rapid power-down condition, as would occur with a power-supply short circuit or with a poorly filtered power supply, the energy stored in C_X could discharge into Pin 2 or 14. To avoid possible device damage in this mode, when C_X is ≥ 0.5 microfarad, a protection diode with a 1-ampere or higher rating (1N5395 or equivalent) and a separate ground return for C_X should be provided as shown in Fig. 17.

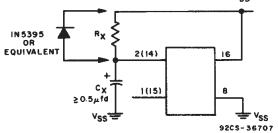


Fig. 17 - Rapid power-down protection circuit.

An alternate protection method is shown in Fig. 18, where a 51-ohm current-limiting resistor is inserted in series with C_x . Note that a small pulse width decrease will occur however, and R_x must be appropriately increased to obtain the originally desired pulse width.

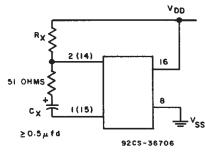
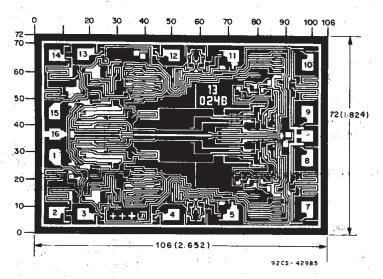


Fig. 18 - Alternate rapid power-down protection circuit.



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils $(10^{-3} inch)$.

Dimensions and pad layout for CD145388H.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9055701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
CD14538BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD14538BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD14538BF	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
CD14538BF3A	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
CD14538BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

26-Sep-2005

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

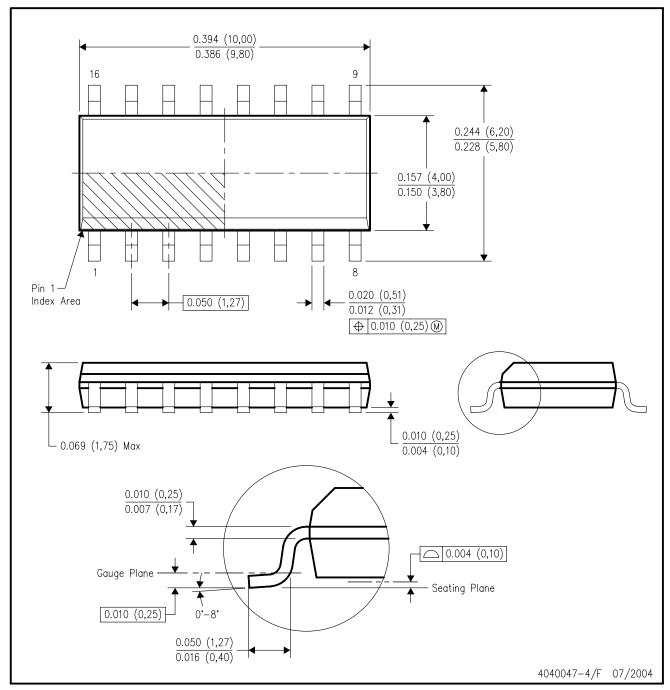


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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